



# **PRODUCT DATASHEET**



- ▶ 5050 IC 1.6t
- Red/Green/Blue

# N0M61S42IC



5050 IC-Integrated Compliant

# **FEATURES:**

- Package: Top View Package with RGB Integrated IC Control
- Forward Current: 12/12/12mA\* \* in order of Red/Green/Blue
- Forward Voltage (typ.): +3.7~+5.3V
- Mixed White Luminous Intensity (typ.): 2000mcd
- Colour: Red/Green/Blue
- Wavelength: 622/522/466nm
- Viewing angle: 120°
- Materials:
  - Resin: Silicone (Water Clear) \_
  - L/F Finish: Ag Plated \_
- Operating Temperature: -40~+85°C
- Storage Temperature: -40~+100°C
- Features: Wide viewing angle and optimized light coupling by inter reflector, the low current requirement makes this device ideal for portable equipment or any other application where power is at premium.
- Pixel: R/G/B 8-bit colour for each chip, total 16M colour can be displayed.
- Soldering methods: IR Reflow soldering
- Preconditioning: acc. to JEDEC Level 4
- Packing: 12mm tape with max.1000pcs/reel, ø180mm (7")

5050 IC-Integrated

Gaming Device •

**APPLICATIONS:** 

Indicator

Telecommunication

Home Appliance

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- Guardrail Tube
- **Button Keys**



## CHARACTERISTICS:

## Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V <sub>DD</sub>	-0 ~ +6.0	V
LED Output Current	Іоит	20	mA
Operating Temperature	Topr	-40~+85	°C
Storage Temperature	Tstg	-40~+100	°C

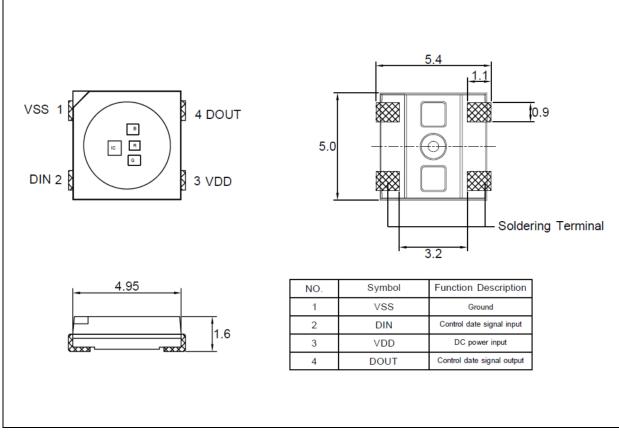
### Electrical & Optical Characteristics (Ta=25°C, V<sub>DD</sub>=5V)

Parameter		Symbol	Values			Unit	Test
		Symbol	Min.	Тур.	Max.	Omt	Condition
Supply Voltage		$V_{\text{DD}}$	3.7	5.0	5.3	V	
Each R/G/B Current		IOL		12		mA	V <sub>DD</sub> =5V
Input High Voltage		VIH	2.7		$V_{\text{DD}}$	V	DI
Input Low Voltage		VIL	0		0.7	V	DI
Luminous Intensity		Iv	1320		3100	mcd	V <sub>DD</sub> =5V
	R			622			
Dominant Wavelength	G	$\lambda_{\text{D}}$		522		nm	V <sub>DD</sub> =5V
	В			466			
Viewing Angle		2 <b>θ</b> 1/2		120		deg	V <sub>DD</sub> =5V



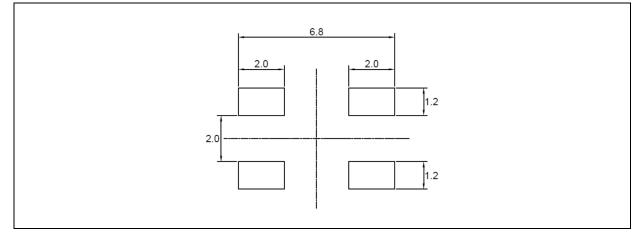
## **OUTLINE DIMENSION:**

#### Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

#### Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance  $\pm 0.1$ mm with angle tolerance  $\pm 0.5^{\circ}$ .



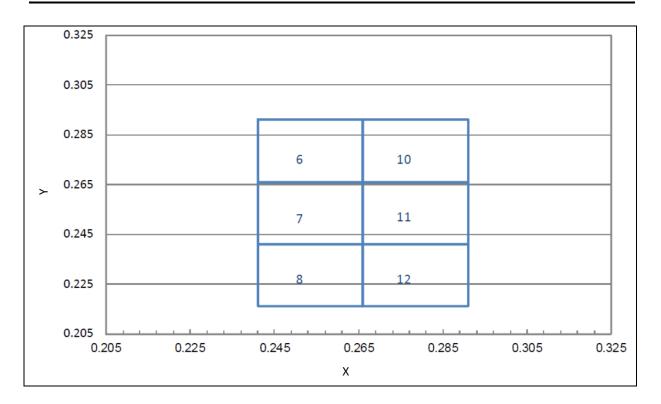
## **BINNING GROUPS:**

### Luminous Intensity Classifications:

Code	Min.	Max.	Unit
H1	1320	1600	
H2	1600	2000	mad
H3	2000	2500	mcd
H4	2500	3100	



## **CIE CHROMATICITY DIAGRAM:**



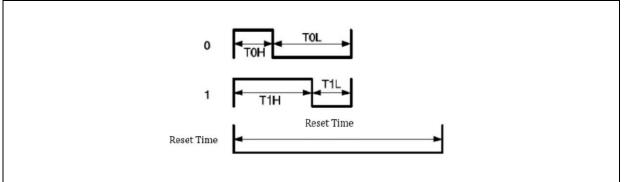
#### Chromaticity Coordinates Classifications:

	1	1		2	3		4	
	Х	Y	Х	Y	Х	Y	Х	Y
6	0.2410	0.2660	0.2410	0.2910	0.2660	0.2910	0.2660	0.2660
7	0.2410	0.2410	0.2410	0.2660	0.2660	0.2660	0.2660	0.2410
8	0.2410	0.2160	0.2410	0.2410	0.2660	0.2410	0.2660	0.2160
10	0.2660	0.2660	0.2660	0.2910	0.2910	0.2910	0.2910	0.2660
11	0.2660	0.2410	0.2660	0.2660	0.2910	0.2660	0.2910	0.2410
12	0.2660	0.2160	0.2660	0.2410	0.2910	0.2410	0.2910	0.2160



# **Function Description:**

#### 1. Timing Wave Form:



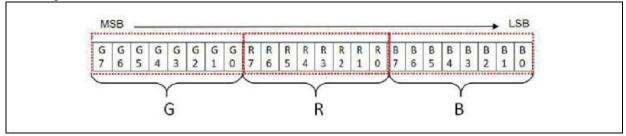
2. High Speed Mode:

Item	Description	min	max	unit
тон	0 code, High-level time	0.22	0.38	us
TOL	0 code, Low-level time	0.58	1	us
T1H	1 code, High-level time	0.58	1	us
T1L	1 code, Low-level time	0.22	1	us
Trst	Reset code,Low-level time	280		us
Note:TH+TL:	>1.2us			

3. Data Communication:

LED11st 24bits2nd 24bits3rd 24bits4th 24bitsTrstLED22nd 24bits3rd 24bits4th 24bitsTrstLED33rd 24bits4th 24bitsTrst
LED3 3rd 24bits 4th 24bits Trst
LED3 3rd 24bits 4th 24bits Trst
LED4 4th 24bits Trst

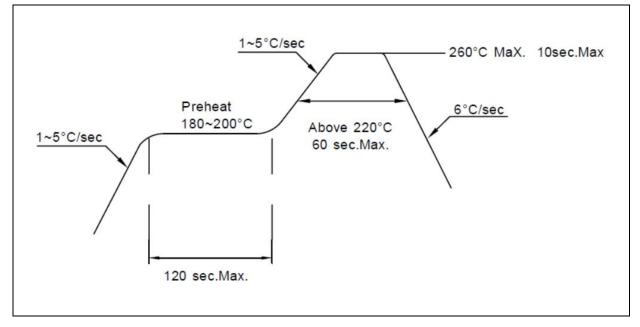
4. Single Data in 24 bits for RGB:





## **RECOMMENDED SOLDERING PROFILE:**





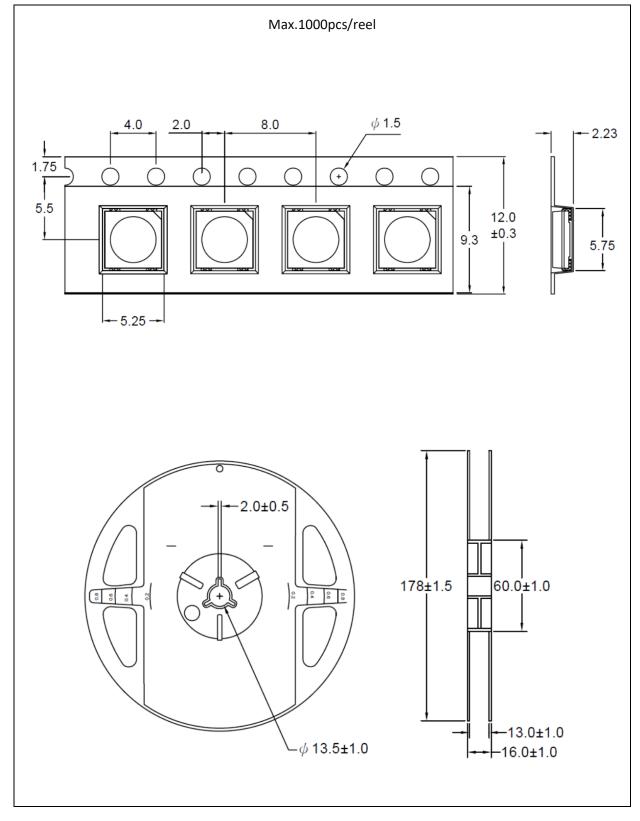
Note:

- 1. We recommend the reflow temperature 240°C (±5°C). The maximum soldering temperature should be limited to 260°C.
- 2. Maxima reflow soldering: 2 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



## **PACKING SPECIFICATION:**

#### Reel Dimension:



## **PRECAUTIONS OF USE:**



#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 24 hours. Otherwise, they should be kept in a damp-proof box with descanting agent stored at R.H.<10% and apply baking before use.

#### **Over-Current Proof:**

Must apply resistors for protection otherwise slight voltage shift will cause big current change and burnout will happen.

#### Baking:

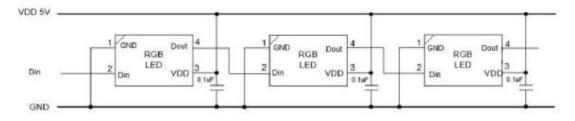
It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

#### **Recommended Route:**

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#### Cleaning:

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Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

#### ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.



## **REVISION RECORD:**

Version	Date	Summary of Revision
A1.0	01/11/2021	Datasheet set-up.
A.1.1	24/09/2022	New datasheet format.